

ITEQ
Your Partner of Advanced Materials & Mass Lam Service

IT-150GTC

Halogen Free Multifunctional Epoxy Resin and Lead Free Laminate & Prepreg

- Halogen Free , Middle Tg and high thermal reliability / Lead-Free Assembly Compatible
- Friendly Processing and CAF Resistance / For low cost HDI process applications

Laminate properties

Items	IPC TM-650	Typical Value	Unit
Peel Strength Standard profile copper foil	2.4.8	6.0	lb/inch
Volume Resistivity	2.5.17.1	10^{10}	MΩ-cm
Surface Resistivity	2.5.17.1	10^{10}	MΩ
Moisture Absorption	2.6.2.1	0.12	%
Permittivity (Dk, 75% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	 2.5.5.9 2.5.5.13 2.5.5.13 2.5.5.13	 3.7 3.6 3.5 3.5	 --
Loss Tangent (Df, 75% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	 2.5.5.9 2.5.5.13 2.5.5.13 2.5.5.13	 0.0137 0.0140 0.0145 0.0148	 --
Flexural Strength A. Length direction B. Cross direction	 2.4.4	 470-500 400-430	 N/mm^2
Thermal Stress 10 s at 288˚C A. Unetched B. Etched	 2.4.13.1	 Pass Pass	 Rating
Flammability	UL94	V-0	Rating
Comparative Tracking Index (CTI)	IEC 60112 / UL 746	CTI 3 (175-249)	Class (Volts)
Maximum Operating Temperature(MOT)	UL 746B	130	˚C
Glass Transition Temperature(DSC)	2.4.25	150	˚C
Decomposition Temperature(5% W.L)	2.4.24.6	365	˚C
X/Y Axis CTE (40℃ to 125℃)	2.4.41	11/12	ppm/˚C
Z-Axis CTE A. Alpha 1 B. Alpha 2 C. 50 to 260 Degrees C	 2.4.24	 35 230 3.1	 ppm/˚C ppm/˚C %
Thermal Resistance A. T260 B. T288	 2.4.24.1	 >60 >60	 Minutes Minutes